

Computational Design Methods for E-Textile

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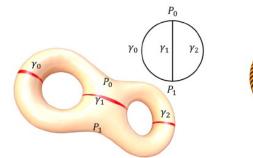
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Design of conformal flexible electronics on free-form 3D surfaces

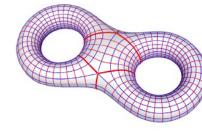
- Computational framework for conformal fabrication based on differential geometry
 - Arbitrary topology
 - Guaranteed smoothness (strip widths control accuracy in high curvature regions)
 - Minimal number of singularities and stress concentration





(a) Pants decomposition and its pants graph





(c) Cylindrical decomposition

(d) Quadrilateral remeshing



electronic circuits



Can generate woven flexible electronics designs

conforming to free-form 3D shapes with 2D printed



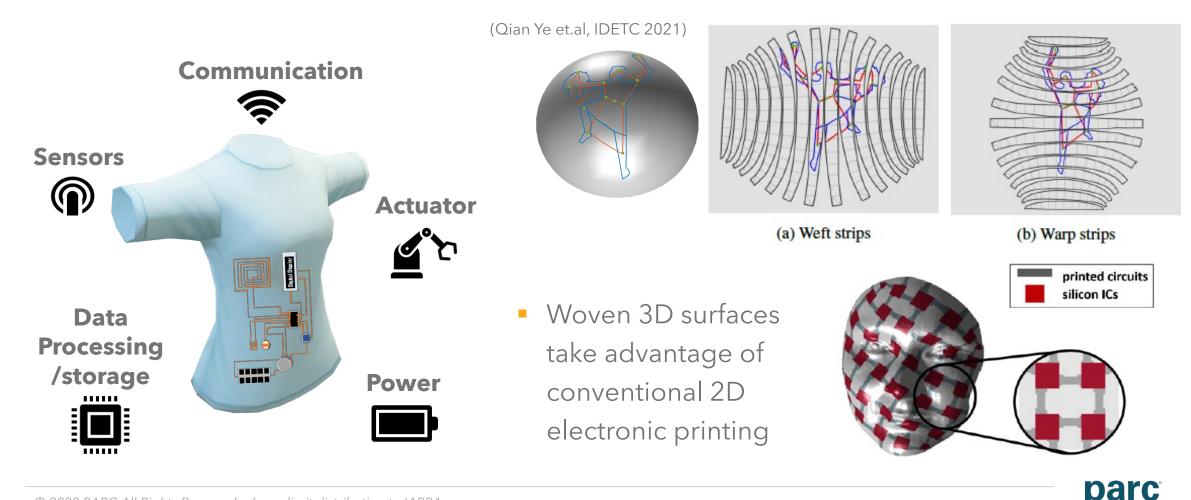


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(Yang Guo, Qian Ye et.al, CMAME 2020)

Fabrication of conformal electronics and system integration

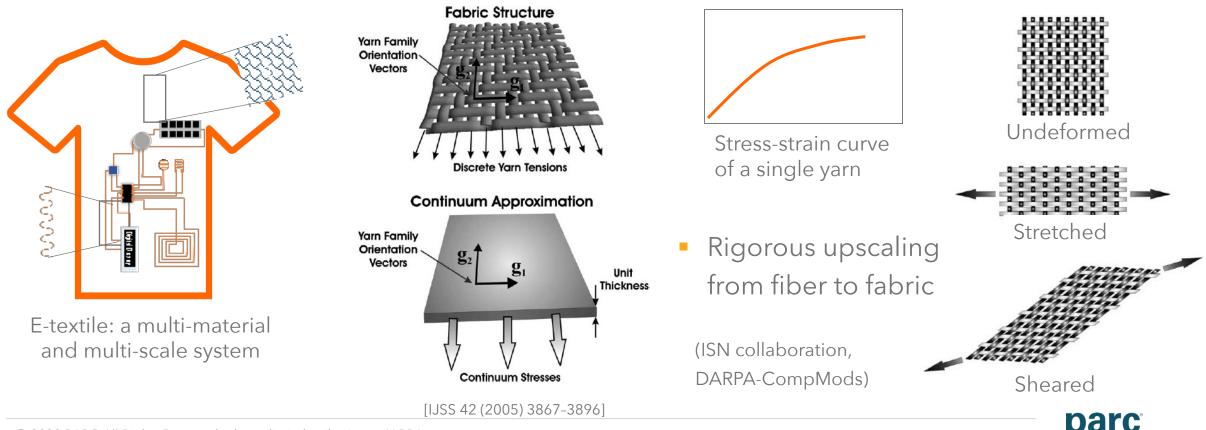
Integration of rigid components by conformal mapping to 3D surface and body movement



Xerox Compan

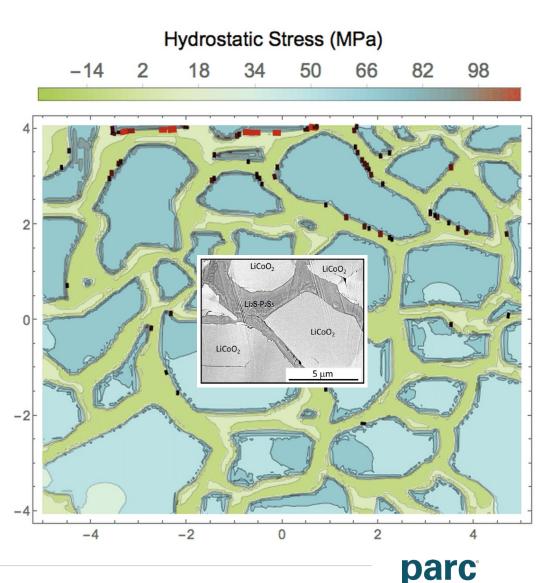
Multiscale mechanical behavior of woven fabrics

- Durability studies of fibers and connection based on multiscale continuum mechanic models
- Sensitivity and reliability of multifunctional fibers in relation to body motion



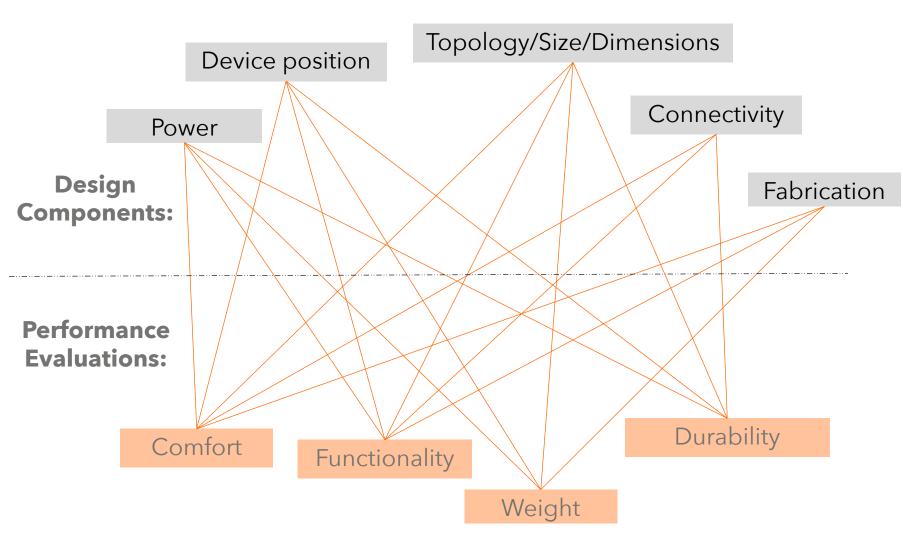
Mesoscale battery design, mechanical degradation

- High energy density solid-state batteries
- Coupling between electrochemistry and mechanics
 - Mechanical compatibility of materials
 - Study of multifunctional materials



[Bucci et al., JPS 441, 2019; Bucci et al., PhysRev Mat 2, 2018; Bucci et al., J Mat ChemA 5, 2017; Bucci et al., JES 164(12), 2017; Bucci et al., JES 164(4), 2017; Bucci et al., ActaMat 62, 2016]

Design tools for the integration of materials and functionalities



Theoretical and computational tools:

- Design of 3D woven structures
- Mechanical response form fiber to fabric to garment
- Multifunctional material modeling
- Topology optimization guided by Al

Theoretical and computational tools in support of SMART e-PANTS:

- **Assembly**: design of 3D woven structures for integration of electronic components by conformal mapping to 3D surface (arbitrary geometries, guaranteed smoothness)
- **Comfort and durability:** analyses of the mechanical response from fiber to fabric to garment-system by rigorous upscaling
- Sensitivity and reliability: modeling of multifunctional fibers, solidstate batteries, and piezoelectric materials under large deformations
- **System design:** topology optimization guided by Al



PARC's hardware capabilities

- **Materials/ chemical synthesis**: Synthesis of novel chemical material in-house, as well as processing capabilities of commercially acquired materials
- **Fiber fabrication:** developed different process methods to fabricate fibers, and fiber like structure with dimensions ranging from 100nm 1um. Different process methods include electrospinning, melt extrusion, melt-electrospinning, solution extrusion, pultrusion, coaxial fiber synthesis etc.
- Device fabrication: nano/micro fabrication capability.
- **Device integration and testing:** PARC has wide range of equipment as well as people-expertise to test different electronic devices. We have fabricated and tested piezoelectric devices, opto-electronic devices, energy generation and storage devices as well as integration capabilities to develop full-fledged electrical circuit.
- **Deformable electronics**: PARC hardware research lab has been working on flexible and stretchable electronics and has in-house capabilities of detailed electro-mechanical testing of the devices.



THANK YOU



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